Abstract of the Disclosure:

A novel method and placement system are configured for populating a substrate with an electronic component. The placement system has a substrate holding device for receiving the substrate, a wafer holding device above the substrate holding device serving for receiving a wafer holding frame, and a vacuum forceps holding device arranged above the wafer holding device. The wafer holding frame can receive a complete semiconductor wafer divided into electronic components.

WHS:nt - MAS-FIN-207F//10/29/2003